

PLATING APPARATUS AND PLATING METHOD

ABSTRACT

To reduce fluctuation of the liquid level of plating solution caused by the operation of a paddle. A plating apparatus for plating a substrate is provided. The plating apparatus includes: a plating bath configured to store plating solution; a paddle that is arranged in the plating bath and configured to stir the plating solution; and a liquid level fluctuation reducing member that is arranged in the plating bath, has a flow path through which the plating solution passes, and is configured to increase a flow rate of the plating solution passing through the flow path to attenuate energy of waves formed by the plating solution.

Representative drawing: Fig. 6